# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]

- HP ENVY
- HP ENVY Notebook
- HP ENVY Notebook 15/ HP ENVY 15
- HP ENVY m6 Notebook
- HP ENVY m6

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing radioactive substances

2.0 Tool Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>Philip #1 / TORX T</td>
</tr>
<tr>
<td>Description #2 screw driver</td>
<td>Philip #0 / TORX T</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Odd Module
2. Remove Log Low
3. Remove Battery
4. Remove IO board
5. Remove Front Speaker & SUBWOOFER
6. Remove HDD Module & RJ45 Door
7. Remove MB & LED board & Card read board
8. Remove lcd Module
9. Remove DC in &K lock & FPR Module
10. Remove TP Module & TP Brk
11. Remove ESD board
12. divide Display assy (TS Remove Lcd Cover/Cover cap)(Non TS Remove Lcd Bezel)
13. divide Display assy (Remove LVDS & Touch Board & Webcam)(Non TS Remove Bezel Trim/Cover cap)
14. divide Display assy (Remove Panel Module)(Non TS Remove Hinge)
15. divide Display assy (Remove touch screen)(Non TS Remove Panel Module)
16. divide Display assy (Remove Hinge & wifi)(Non TS Remove LVDS & Webcam & wifi)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

PSG instructions for this template are available at EL-MF877-01
Step 1 Remove Odd Module

Step 2 Remove Log Low

Step 3 Remove Battery

Step 4 Remove IO board

Step 5 Remove Front Speaker & SUBWOOFER

Step 6 Remove HDD Module & RJ45 Door

PSG instructions for this template are available at EL-MF877-01
Step 7 Remove MB & LED board. & Card read board

Step 8 Remove lcd Module

Step 9 Remove DC in &K lock & FPR Module

Step 10 Remove TP Module & TP Brk

Step 11 Remove ESD board

Step 12 Remove Lcd Cover/Cover cap(TS) Remove Lcd Bezel (Non TS)

PSG instructions for this template are available at EL-MF877-01
Step 13 Remove LVDS&Touch Board & Webcam(TS)  Remove Bezel Trim/Cover cap (Non TS)

Step14 Remove Panel Module (TS)   Remove Hinge (Non TS)
Step 15 Remove touch screen (TS)

Step 16 Remove Hinge & wifi (TS)   Remove LVDS & Webcam & wifi (Non TS)

PSG instructions for this template are available at EL-MF877-01